



Case: AMKOR-052A

#23/AmdtC
(NO)
7-25-03
C. Moore

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Tae Heon Lee et al.)	Group No.:	2814
Serial No.:	09/687,048)		
Filed:	10/13/2000)	Examiner:	Nguyen,
For:	Leadframe and Semiconductor Package)		Dilinh P.
	with Improved Solder Joint Strength)		

M. Baunson
9/26/03

AMENDMENT AFTER FINAL ACTION PURSUANT TO 37 C.F.R. § 1.116

Mail Stop AF
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir/Madam:

Applicant acknowledges, with appreciation, the time taken by Examiner Nguyen to telephonically interview the present application with Applicant's counsel on July 8, 2003. As a result of this telephonic interview, Applicant respectfully requests that the present application be amended as follows:

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AF/2800

PTO/SB/21 (08-00)

Approved for use through 10/31/2002. OMB 0651-0031

U.S. Patent and Trademark Office: U.S. DEPARTMENT OF COMMERCE

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TRANSMITTAL FORM <i>(to be used for all correspondence after initial filing)</i>	Application Number	09/687,048	
	Filing Date	10/13/00	
	First Named Inventor	Tae Heon Lee et al.	
	Group Art Unit	2814	
	Examiner Name	Dilinh P. Nguyen	
Total Number of Pages in This Submission		Attorney Docket Number	AMKOR-052A

ENCLOSURES (check all that apply)		
<input type="checkbox"/> Fee Transmittal Form <input type="checkbox"/> Fee Attached <input checked="" type="checkbox"/> Amendment / Reply <input checked="" type="checkbox"/> After Final <input type="checkbox"/> Affidavits/declaration(s) <input type="checkbox"/> Extension of Time Request <input type="checkbox"/> Express Abandonment Request <input type="checkbox"/> Information Disclosure Statement <input type="checkbox"/> Certified Copy of Priority Document(s) <input type="checkbox"/> Response to Missing Parts/ Incomplete Application <input type="checkbox"/> Response to Missing Parts under 37 CFR 1.52 or 1.53	<input type="checkbox"/> Assignment Papers (for an Application) <input type="checkbox"/> Drawing(s) <input type="checkbox"/> Licensing-related Papers <input type="checkbox"/> Petition <input type="checkbox"/> Petition to Convert to a Provisional Application <input type="checkbox"/> Power of Attorney, Revocation Change of Correspondence Address <input type="checkbox"/> Terminal Disclaimer <input type="checkbox"/> Request for Refund <input type="checkbox"/> CD, Number of CD(s) _____	<input type="checkbox"/> After Allowance Communication to Group <input type="checkbox"/> Appeal Communication to Board of Appeals and Interferences <input type="checkbox"/> Appeal Communication to Group (Appeal Notice, Brief, Reply Brief) <input type="checkbox"/> Proprietary Information <input type="checkbox"/> Status Letter <input checked="" type="checkbox"/> Other Enclosure(s) (please identify below): Certificate of Mailing, Return Receipt Postcard
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SIGNATURE OF APPLICANT, ATTORNEY, OR AGENT	
Firm or Individual name	Mark B. Garred STETINA BRUNDA GARRED & BRUCKER
Signature	
Date	7/9/03

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Signature		Date	7/9/03

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ATTORNEY DOCKET NO: AMKOR-052A

TITLE: LEAD FRAME AND SEMICONDUCTOR PACKAGE WITH IMPROVED
SOLDER JOINT STRENGTH

Certificate of Mailing under 37 CFR 1.8 or 37 CFR 1.10

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Andrea K. Treitler
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